

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) A lead-free solder consisting essentially of:

- (a) 1.0 to 2.0[[2.99]] wt.% of Ag;
- (b) 0.4 to 0.9[[1.3]] wt.% of Cu;
- (c) 0.02 to 0.06 wt.% of Ni; and
- (d) a balance of Sn;

wherein said Ni ~~serves to lower the copper dissolution rate of said~~ solder has a liquidus temperature of 240°C or lower.

2. (Previously presented) The solder according to claim 1, wherein the content of Ni is in a range from 0.02 to 0.04 wt.%.

3. (Currently amended) The solder according to claim 1, wherein said solder having a copper dissolution rate of 0.20 µm/sec or less.

4. (Canceled)

5. (Previously presented) The solder according to claim 1, wherein said solder having a liquidus temperature of 230°C or lower.

6. (Previously presented) The solder according to claim 1, wherein said solder has a viscosity of 2.5 cP or lower.

7. (Canceled)

8. (Currently Amended) The solder according to claim 1, further containing 0.02 to 0.06[[0.05]]

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wt.% of Fe.

Claims 9-24. (Canceled)